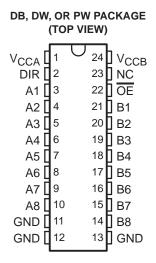
SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE

- Controlled Baseline
 One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Bidirectional Voltage Translator
- 2.3 V to 3.6 V on A Port and 3 V to 5.5 V on B Port
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- Latch-Up Performance Exceeds 250 mA Per JESD 17

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- ESD Protection Exceeds JESD 22
 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005



NC - No internal connection

description/ordering information

This 8-bit (octal) noninverting bus transceiver contains two separate supply rails. The B port is designed to track V_{CCB} , which accepts voltages from 3 V to 5.5 V, and the A port is designed to track V_{CCA} , which operates at 2.3 V to 3.6 V. This allows for translation from a 3.3-V to a 5-V system environment and vice versa, from a 2.5-V to a 3.3-V system environment and vice versa.

The SN74LVCC3245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are isolated. The control circuitry (DIR, \overline{OE}) is powered by V_{CCA}.

TA	PACKAGE	†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC – DW	Reel of 2000	CLVCC3245AIDWREP	LVCC3245A
–40°C to 85°C	SSOP – DB	Reel of 2000	CLVCC3245AIDBREP	LH245AEP
	TSSOP – PW	Reel of 2000	CLVCC3245AIPWREP	LH245AEP

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

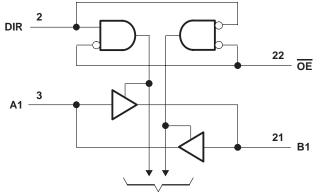
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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FUNCTION TABLE (each transceiver)									
INP	UTS								
OE	DIR	OPERATION							
L	L	B data to A bus							
L	Н	A data to B bus							
н	Х	Isolation							

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CCA} and V_{CCB} Input voltage range, V_{I} : All A ports (see Note 1) All B ports (see Note 2) Except I/O ports (see Note 1) Output voltage range, V_{O} (see Note 2): All A ports All B ports Input clamp current, I_{IK} ($V_{I} < 0$) Output clamp current, I_{OK} ($V_{O} < 0$) Continuous output current, I_{O} Continuous current through V_{CCA} , V_{CCB} , or GND Package thermal impedance, θ_{JA} (see Note 3): DB package DW package PW package	$\begin{array}{c} -0.5 \ V \ to \ V_{CCA} + 0.5 \ V \\ -0.5 \ V \ to \ V_{CCB} + 0.5 \ V \\ -0.5 \ V \ to \ V_{CCA} + 0.5 \ V \\ -0.5 \ V \ to \ V_{CCA} + 0.5 \ V \\ -0.5 \ V \ to \ V_{CCB} + 0.5 \ V \\ -0.5 \ V \ to \ V_{CCB} + 0.5 \ V \\ -0.5 \ W \ to \ V_{CCB} + 0.5 \ W \\ -0.5 \ W \ to \ V_{CCB} + 0.5 \ W \\ -0.5 \ W \ to \ V_{CCB} + 0.5 \ W \\ -0.5 \ W \ to \ V_{CCB} + 0.5 \ W \\ -0.5 \ W \ to \ V_{CCB} + 0.5 \ W \\ -0.5 \ W \ to \ V_{CCB} + 0.5 \ W \\ -0.5 \ W \ to $
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. This value is limited to 4.6 V maximum.

2. This value is limited to 6 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE

AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005

recommended operating conditions (see Note 4)

		VCCA	V _{CCB}	MIN	NOM	MAX	UNIT
VCCA	Supply voltage			2.3	3.3	3.6	V
Vссв	Supply voltage			3	5	5.5	V
		2.3 V	3 V	1.7			
. ,		2.7 V	3 V	2			.,
VIHA	High-level input voltage	3 V	3.6 V	2			V
	HA High-level input voltage HB High-level input voltage LA Low-level input voltage LB Low-level input voltage	3.6 V	5.5 V	2			
		2.3 V	3 V	2			
	Lifety Level Construction	2.7 V	3 V	2			
VIHB	Hign-level input voltage	3 V	3.6 V	2			V
		3.6 V	5.5 V	3.85			
		2.3 V	3 V			0.7	
		2.7 V	3 V			0.8	V
VILA	Low-level input voltage	3 V	3.6 V			0.8	V
		3.6 V	5.5 V			0.8	
	Low-level input voltage	2.3 V	3 V			0.8	
		2.7 V	3 V			0.8	V
VILB	Low-level input voltage	3 V	3.6 V			0.8	V
	A Low-level input voltage B Low-level input voltage High-level input voltage (control pins) (Referenced to V _{CCA}) Low-level input voltage (control pins)	3.6 V	5.5 V			1.65	
		2.3 V	3 V	1.7			
V	High-level input voltage (control pins)	2.7 V	3 V	2			V
VIH	(Referenced to V _{CCA})	3 V	3.6 V	2			v
		3.6 V	5.5 V	2			
		2.3 V	3 V			0.7	
v		2.7 V	3 V			0.8	V
VIL	(Referenced to V_{CCA})	3 V	3.6 V			0.8	V
		3.6 V	5.5 V			0.8	
VIA	Input voltage			0		VCCA	V
V _{IB}	Input voltage			0		V _{CCB}	V
VOA	Output voltage			0		VCCA	V
Vов	Output voltage	İ		0		VCCB	V

NOTE 4: All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN74LVCC3245A-EP **OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE** AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005

recommended operating conditions (see Note 4) (continued)

		VCCA	VCCB	MIN	NOM	MAX	UNIT
		2.3 V	3 V			-8	
IOHA	High-level output current	2.7 V	3 V			-12	mA
		3.3 V	3 V			-24	
		2.3 V	3.3 V			-12	
ІОНВ Н	High-level output current	2.7 V	3.3 V			-12	mA
		3.3 V	3 V			-24	
		2.3 V	3 V			8	
IOLA	Low-level output current	2.7 V	3 V			12	mA
		3.3 V	3 V			24	
		2.3 V	3.3 V			12	
IOLB	Low-level output current	2.7 V	3.3 V			12	mA
		3.3 V	3 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate					10	ns/V
ТА	Operating free-air temperature			-40		85	°C

NOTE 4: All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE

AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005

electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					-	•	

PAF	RAMETER	TEST CONDITIONS	VCCA	V _{CCB}	MIN	TYP	MAX	UNIT	
		I _{OH} = -100 μA	3 V	3 V	2.9	3			
		$I_{OH} = -8 \text{ mA}$	2.3 V	3 V	2				
			2.7 V	3 V	2.2	2.5			
VOHA		$I_{OH} = -12 \text{ mA}$	3 V	3 V	2.4	2.8		V	
			3 V	3 V	2.2	2.6			
		I _{OH} = -24 mA	$\begin{array}{c c c c c c c c c c c c c c c c c c c $						
		I _{OH} = -100 μA	3 V	3 V	2.9	3			
		10	2.3 V	3 V	2.4				
Vонв		I _{OH} = -12 mA	2.7 V	3 V	2.4	2.8		V	
		1	3 V	3 V	2.2	2.6			
		I _{OH} = -24 mA	$ \begin{array}{c} 2.3 \lor \\ 2.7 \lor \\ 3 \lor \\ 2.7 \lor \\ 3 \lor \\ 2.7 \lor \\ 4.5 \lor \\ 2.7 \lor \\ 4.5 \lor \\ 4.5 \lor \\ 3 \lor \\ $			4.2			
		I _{OL} = 100 μA	3 V	3 V			0.1		
		I _{OL} = 8 mA	2.3 V	3 V			0.6		
Vola		I _{OL} = 12 mA	2.7 V	3 V		0.1	0.5	V	
		lo: - 24 mA	3 V	3 V		0.2	0.5		
		I _{OL} = 24 mA	2.7 V	4.5 V		0.2	0.5		
		I _{OL} = 100 μA	3 V	3 V			0.1		
		I _{OL} = 12 mA	2.3 V	3 V			0.4	V	
Volb	$l_{0} = 24 \text{ mA}$	21/	3 V		0.2	0.5	v		
	I _{OL} = 24 mA	3 V	4.5 V		0.2	0.5			
	Control inpute		261/	3.6 V		±0.1	±1	^	
1	Control inputs	V _I = V _{CCA} or GND	3.0 V	5.5 V		±0.1	±1	μA	
loz†	A or B ports	$V_{O} = V_{CCA/B}$ or GND, $V_{I} = V_{IL}$ or V_{IH}	3.6 V	3.6 V		±0.5	±5	μΑ	
		A port = V_{CCA} or GND, $I_0 = 0$	3.6 V	Open		5	50		
ICCA	B to A		0.01/	3.6 V		5	50	μA	
		B port = V_{CCB} or GND, $I_O = 0$	3.6 V	5.5 V	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	50			
	A to D		261/	3.6 V		5	50	^	
ІССВ	A to B	A port = V_{CCA} or GND, $I_0 = 0$	3.6 V	5.5 V		8	80	μA	
	A port	V_{I} = V _{CCA} – 0.6 V, Other inputs at V _{CCA} or GND, OE at GND and DIR at V _{CCA}	3.6 V	3.6 V		0.35	0.5		
∆ICCA [‡]	OE	$V_I = V_{CCA} - 0.6$ V, Other inputs at V_{CCA} or GND, DIR at V_{CCA}	3.6 V	3.6 V		0.35	0.5	mA	
	DIR	$\frac{V_{I}}{OE}$ = V _{CCA} – 0.6 V, Other inputs at V _{CCA} or GND, OE at GND	3.6 V	3.6 V		0.35	0.5		
∆ICCB‡	B port	V_L = V _{CCB} – 2.1 V, Other inputs at V _{CCB} or GND, OE at GND and DIR at GND	3.6 V	5.5 V		1	1.5	mA	
Ci	Control inputs	VI = V _{CCA} or GND	Open	Open		4		pF	
C _{io}	A or B ports	$V_{O} = V_{CCA/B}$ or GND	3.3 V	5 V		18.5		pF	

[†] For I/O ports, the parameter I_{OZ} includes the input leakage current.
 [‡] This is the increase in supply current for each input that is at one of the specified voltage levels, rather than 0 V or the associated V_{CC}.



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCA} = 2.5 V \\ \pm 0.2 V, \\ V_{CCB} = 3.3 V \\ \pm 0.3 V$		± 0.5 V		TO 3.6 V, V _{CCB} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
^t PHL	•	6	1	9.4	1	6	1	7.1	
^t PLH	A	В	1	9.1	1	5.3	1	7.2	ns
t _{PHL}	D	А	1	11.2	1	5.8	1	6.4	
^t PLH	В	~	1	9.9	1	7	1	7.6	ns
^t PZL	OE	•	1	14.5	1	9.2	1	9.7	
^t PZH	ÛE	A	1	12.9	1	9.5	1	9.5	ns
t _{PZL}	OE	6	1	13	1	8.1	1	9.2	
^t PZH	ÛE	В	1	12.8	1	8.4	1	9.9	ns
^t PLZ	OE		1	7.1	1	7	1	6.6	
^t PHZ	UE	А	1	6.9	1	7.8	1	6.9	ns
^t PLZ	OE	P	1	8.8	1	7.3	1	7.5	
^t PHZ	UE	В	1	8.9	1	7	1	7.9	ns

operating characteristics, V_{CCA} = 3.3 V, V_{CCB} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT	
		Outputs enabled	0 50	6 40 MUL	38	pF
Cpd	Power dissipation capacitance per transceiver	Outputs disabled	$C_{L} = 50,$	f = 10 MHz	4.5	

power-up considerations[†]

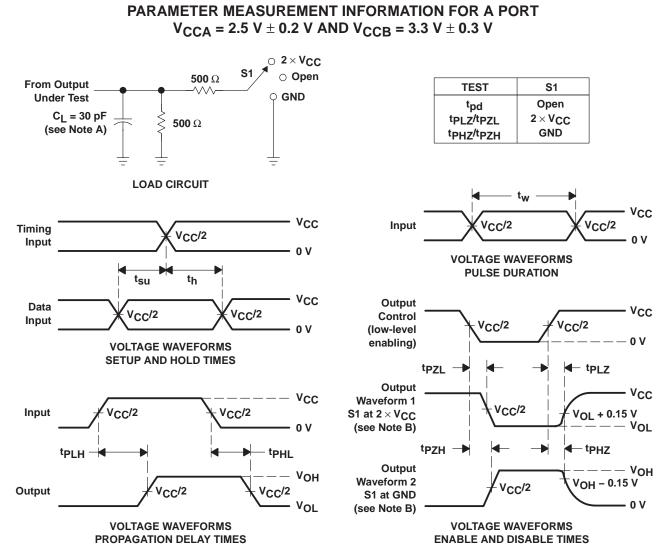
TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. To guard against such power-up problems, take these precautions:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device (V_{CCA} for all four of these devices).
- 3. Tie \overline{OE} to V_{CCA} with a pullup resistor so that it ramps with V_{CCA}.
- Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), 4. ramp it with V_{CCA}. Otherwise, keep DIR low.

[†]Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.



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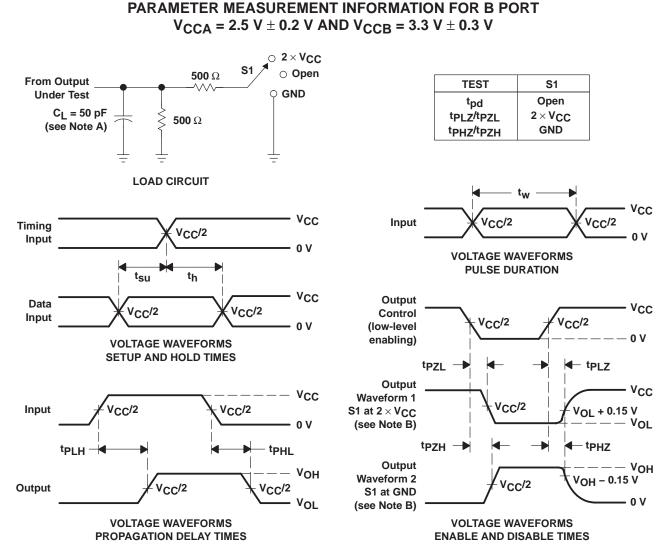


- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tpLH and tpHL are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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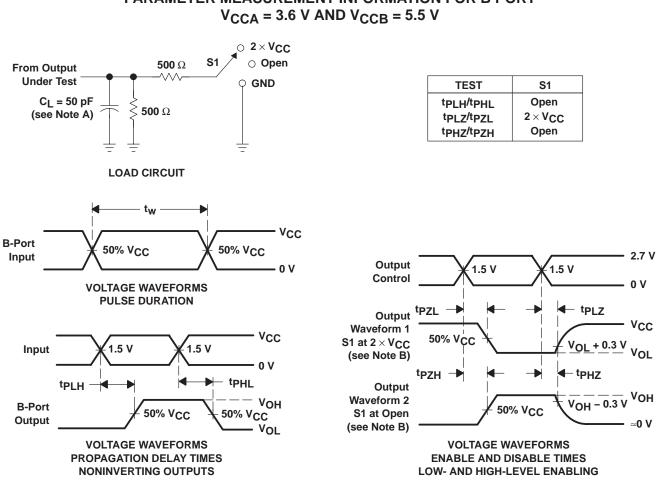


- NOTES: A. Cl includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. tPLZ and tPHZ are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



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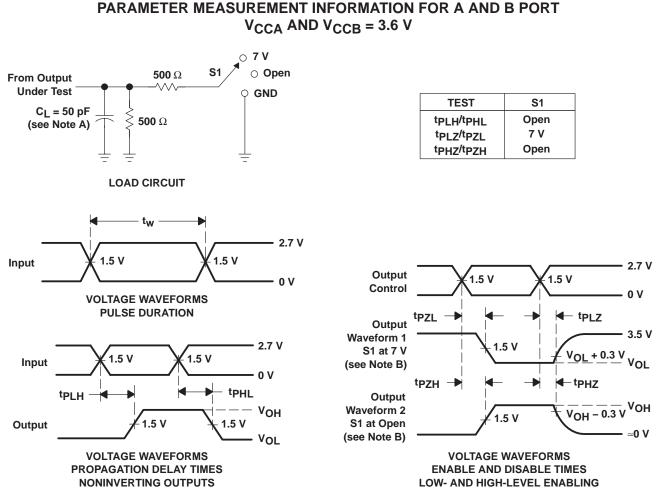
PARAMETER MEASUREMENT INFORMATION FOR B PORT

- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms



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- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms



V IEXAS

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CLVCC3245AIDBREP	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CLVCC3245AIDWREP	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CLVCC3245AIPWREP	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/05602-01XE	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/05602-01YE	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/05602-01ZE	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVCC3245A-EP :

Catalog: SN74LVCC3245A

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

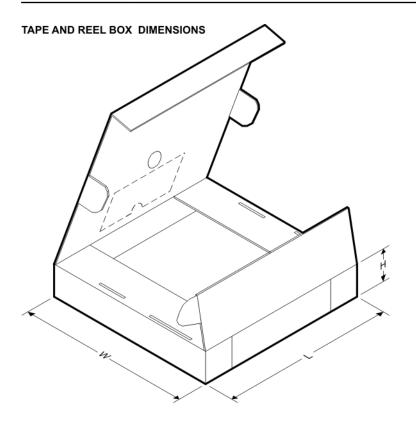


*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVCC3245AIDBREP	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CLVCC3245AIDWREP	SOIC	DW	24	2000	330.0	24.4	10.85	15.8	2.7	12.0	24.0	Q1
CLVCC3245AIPWREP	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

26-Jul-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CLVCC3245AIDBREP	SSOP	DB	24	2000	346.0	346.0	33.0
CLVCC3245AIDWREP	SOIC	DW	24	2000	346.0	346.0	41.0
CLVCC3245AIPWREP	TSSOP	PW	24	2000	346.0	346.0	33.0

MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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